#### 506699019 06/04/2021

### PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

#### **CONVEYING PARTY DATA**

Name	Execution Date
YUE LI	06/02/2021
DONG QIAN	06/02/2021
GANG LIU	06/02/2021

### **RECEIVING PARTY DATA**

Name:	SHANGHAI TIANMA AM-OLED CO.,LTD.	
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City:	SHANGHAI	
State/Country:	CHINA	
Postal Code:	201201	
Name:	TIANMA MICRO-ELECTRONICS CO., LTD.	
Street Address:	22/F, HANGDU BUILDING, SHENNAN ROAD, FUTIAN DISTRICT	
City:	SHENZHEN	
State/Country:	CHINA	
Postal Code:	518052	

#### **PROPERTY NUMBERS Total: 1**

Property Type	Number
Application Number:	17339240

#### CORRESPONDENCE DATA

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NAME OF SUBMITTER:	XIXI AI
SIGNATURE:	/XIXI AI/

**PATENT** REEL: 056442 FRAME: 0170 506699019

DATE SIGNED: 06/04/2021

Total Attachments: 2
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PATENT REEL: 056442 FRAME: 0171

# ASSIGNMENT AND DECLARATION

WHEREAS I/We, the below named inventor(s) (hereinafter referred to as Assignor(s)) have made an invention entitled:

## DISPLAY PANEL, SHIFT REGISTER CIRCUIT AND DRIVING METHOD THEREOF

for which I/We executed an application for United States Letters Patent concurrently herewith or filed an application for United States Letters Patent on (Application No); and
WHEREAS, <u>Shanghai Tianma AM-OLED Co.,Ltd.</u> , a corporation of <u>P.R. China</u> whose post office address is <u>Room 509 · Building 1 · No.6111 Longdong Rd.,Pudong Dist.,Shanghai, China 201201</u> , and
<u>Tianma Micro-Electronics Co., Ltd.</u> , a corporation of <u>P.R. China</u> whose post office address is <u>22/F</u> , <u>Hangdu Building, Shennan Road, Futian District, Shenzhen, China</u> , <u>518052</u> (hereinafter referred to as Assignees), are desirous of securing the entire right, title, and interest in and to this invention in all countries throughout the world, and in and to the application for United States Letters Patent on this invention and the Letters Patent to be issued upon this application;
NOW THEREFORE, be it known that, for good and valuable consideration the receipt of which from Assignee is hereby acknowledged, I/We, as Assignor(s), have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto the Assignee, its lawful successors and assigns, my/our entire right, title, and interest in and to this invention, provisional Application No, filed (if any), and this application, and all divisions, substitutions, continuations, and continuations-in-part thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof, and all rights to claim priority on the basis of the above provisional application (if any), as well as all rights to claim priority on the basis of this application, and all applications for Letters Patent which may hereafter be filed for this invention in any foreign country and all Letters Patent which may be granted on this invention in any foreign country, and all extensions, renewals, and reissues thereof; and I/We hereby authorize and request the Commissioner of Patents and Trademarks of the United States and any official of any foreign country whose duty it is to issue patents on applications as described above, to issue all Letters Patent for this invention to Assignee, its successors and assigns, in accordance with the terms of this Assignment;
AND, I/WE HEREBY covenant that I/We have the full right to convey the interest assigned by this Assignment, and I/We have not executed and will not execute any agreement in conflict with this Assignment;
AND, I/WE HEREBY further covenant and agree that I/We will, without further consideration, communicate with Assignee, its successors and assigns, any facts known to me/us respecting this invention, and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver any and all papers that may be necessary or desirable to perfect the title to this invention in said Assignee, its successors or assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid Assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States and any foreign country, it being understood that any expense incident to the execution of such papers shall be borne by the Assignee, its successors and assigns.
AND, I/WE HEREBY authorize and request the attorneys I/we have empowered in the Declaration and Power of Attorney in this application, to insert here in parentheses (Application No. $\underline{17339240}$ filed $\underline{04\text{-}JUN\text{-}2021}$ ) the filing date and application number of said application when known.

Anova Law Group, PLLC 00189 0171,01US

RECORDED: 06/04/2021

Further, as a below named inventor, I hereby declare that:

This declaration is directed to the application attached hereto or United States application or	
international application number filed on	
If the application is not attached hereto, the application is as identified above or by the attorney dock	et
number as set forth above and/or the following.	

The above-identified application was made or authorized to be made by me.

I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.

I have reviewed and understand the contents of the above-identified application, including the claims.

I acknowledge the duty to disclose information which is material to patentability as defined in Title 37,Code of Federal Regulations § 1.56, including for continuation-in-part applications, material information which became available between the filling data of the prior application and the national or PCT International filling date of the continuation-in-part application.

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. §1001 by fine or imprisonment of not more than five (5) years, or both.

IN TESTIMONY WHEREOF, I/We have hereunto set our hands.

Inventor 1 Legal Name:	Yue.Li			
Signature:	Jue D	Dale:	2021/6/z	
Inventor 2 Legal Name:	Dong QIAN			
Signature:	Day RIAI	Date:	2021.6.2	
Inventor 3 Legal Name:	Gang LIU			
Signature:	Good bu	Date:	002/.6.2	